Product Summary

BV_{DSS}	$R_{DS(ON)}$ Max	I_D T_C = +25°C
1200V	80.5mΩ @ V_{GS} = 18V	44.5

Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/**

Description and Applications

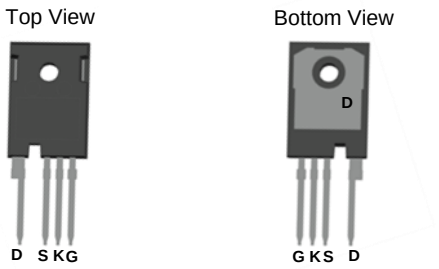
This SiC MOSFET is designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- SMPS (switching mode power supplies)
- UPS (uninterruptable power supplies)
- Energy storages
- EV charging systems
- Solar inverters

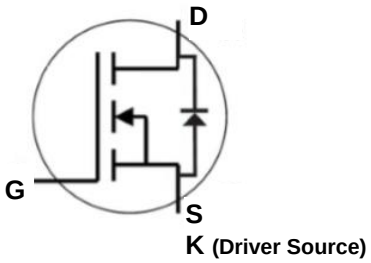
Mechanical Data

- Package: TO247-4
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e3
- Weight: 6.6 grams (Approximate)

TO247-4 Standard



Pin Configuration



Internal Schematic

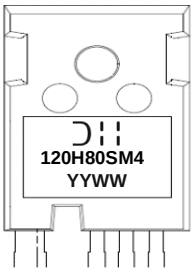
Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
DMWSH120H80SM4	TO247-4 Standard	30 Pieces	Tube

Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

TO247-4 Standard



= Manufacturer's Marking
120H80SM4 = Product Type Marking Code
YYWW or YYWW = Date Code Marking
YY or YY = Last Two Digits of Year (ex: 24 = 2024)
WW or WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	1200	V
Gate-Source Voltage		V_{GS}	-10/+22	V
Gate-Source Voltage (recommended operating values)		V_{GS}	-4/+18	V
Gate-Source Transient Voltage, t_P < 1µs, t ≤ 10 Hours Over Lifetime		V_{GS}	-11/+25	V
Continuous Drain Current (Notes 5, 6)	T_C = +25°C T_C = +100°C	I_D	44.5 31.4	A
Continuous Diode Forward Current (Note 5)		I_S	34	A
Pulsed Source Current (Pulse Width t_P Limited by $T_{J\,Max}$) (Note 5)		I_{SM}	80	A
Pulsed Drain Current (Pulse Width t_P Limited by $T_{J\,Max}$) (Note 5)		I_{DM}	80	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T_C = +25°C	P_D	238	W
	T_C = +100°C		119	
Thermal Resistance, Junction to Ambient (Note 7)		$R_{\theta JA}$	28	°C/W
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	0.63	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	1200	—	—	V	V_{GS} = 0, I_D = 100µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	50	µA	V_{DS} = 1200V, V_{GS} = 0
Gate-Source Leakage	I_{GSS}	—	—	±200	nA	V_{GS} = +18/-4V, V_{DS} = 0
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(TH)}$	1.7	2.5	3.5	V	V_{DS} = V_{GS}, I_D = 5mA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	62	80.5	mΩ	V_{GS} = 18V, I_D = 20A
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	75	—	mΩ	V_{GS} = 15V, I_D = 20A
Diode Forward Voltage	V_{SD}	—	4.5	—	V	V_{GS} = -4V, I_S = 10A
Transconductance	gfs	—	4.2	—	S	V_{DS} = 20V, I_D = 20A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	1069	—	pF	V_{GS} = 0, V_{DS} = 1000V V_{AC} = 25mV, f = 1MHz
Output Capacitance	C_{oss}	—	56	—		
Reverse Transfer Capacitance	C_{rss}	—	4.17	—		
C_{oss} Stored Energy	E_{oss}	—	34.3	—	µJ	
Turn-On Switching Energy (Body Diode Forward)	E_{ON}	—	105	—	µJ	V_{GS} = -4V/+18V, V_{DS} = 800V R_g = 5Ω, I_D = 20A, L = 156µH
Turn-Off Switching Energy (Body Diode Forward)	E_{OFF}	—	68	—		
Gate Resistance	R_g	—	2.7	—	Ω	V_{AC} = 100mV, f = 1MHz
Total Gate Charge	Q_g	—	59.1	—	nC	V_{GS} = -4V/+18V, V_{DS} = 800V I_D = 20A
Gate-Source Charge	Q_{gs}	—	16.6	—		
Gate-Drain Charge	Q_{gd}	—	20.0	—		
Turn-On Delay Time	$t_{D(ON)}$	—	8.1	—	ns	V_{GS} = -4V/+18V, V_{DS} = 800V R_g = 5Ω, I_D = 20A Inductive Load
Turn-On Rise Time	t_R	—	17.1	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	19.6	—		
Turn-Off Fall Time	t_F	—	7.0	—		
Body Diode Reverse-Recovery Time	t_{RR}	—	12.2	—	ns	V_{GS} = -4V, V_{DS} = 800V I_F = 20A, di/dt = 3600A/µs
Body Diode Reverse-Recovery Charge	Q_{RR}	—	152	—	nC	
Body Diode Reverse-Recovery Current	I_{RRM}	—	20.4	—	A	

Notes:
5. Device mounted on an infinite heatsink.
6. Drain current limited by maximum junction temperature.
7. Device mounted on FR-4 substrate PC board, 2oz. copper, with minimum recommended pad layout.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to production testing.

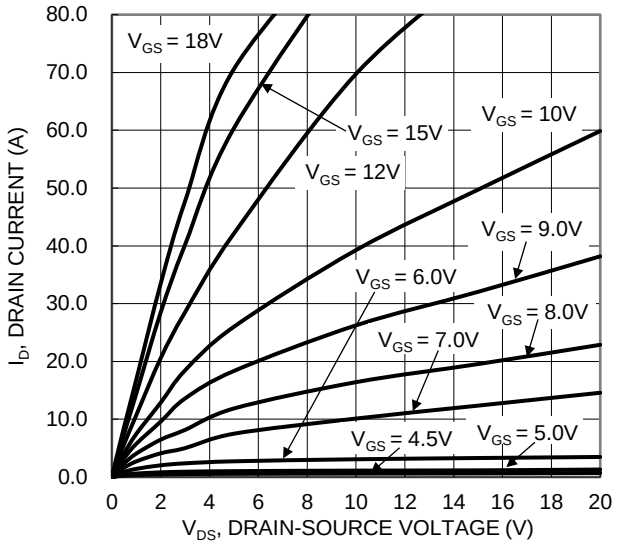


Figure 1. Typical Output Characteristic

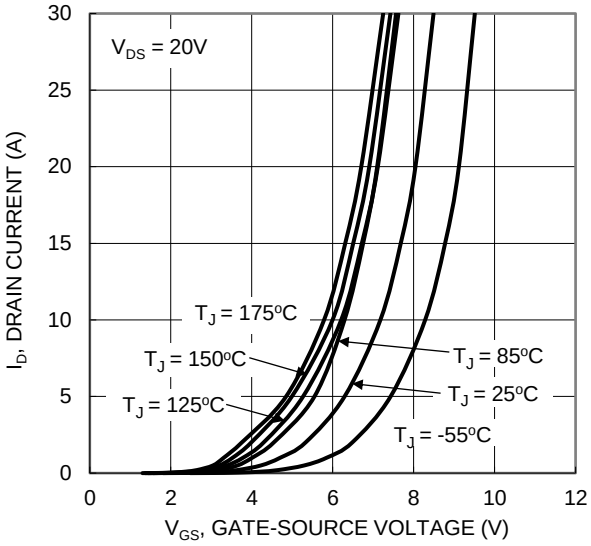


Figure 2. Typical Transfer Characteristic

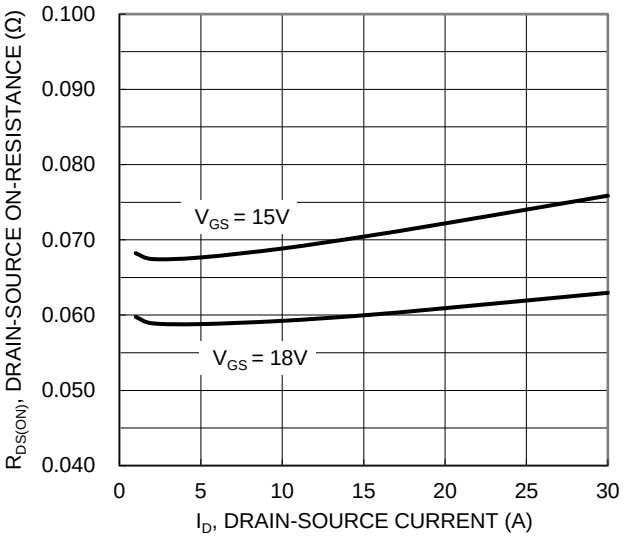


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

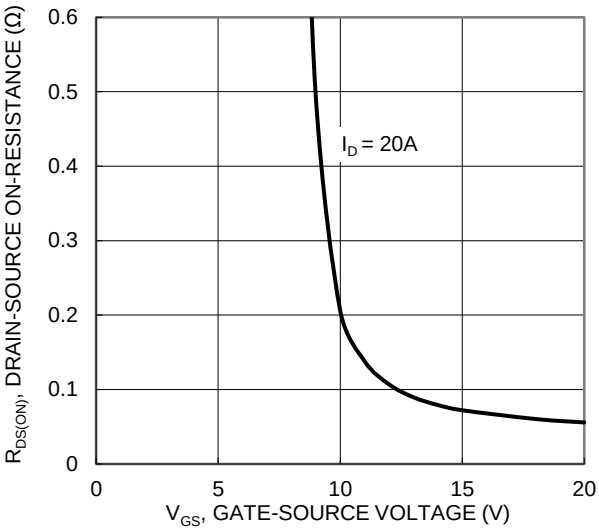


Figure 4. Typical Transfer Characteristic

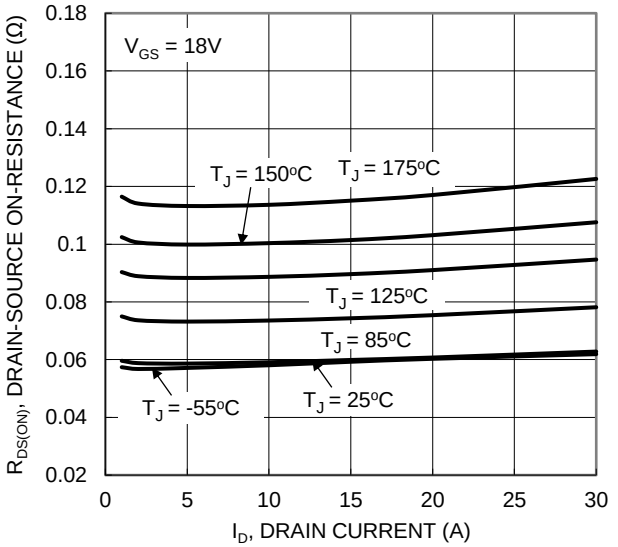


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

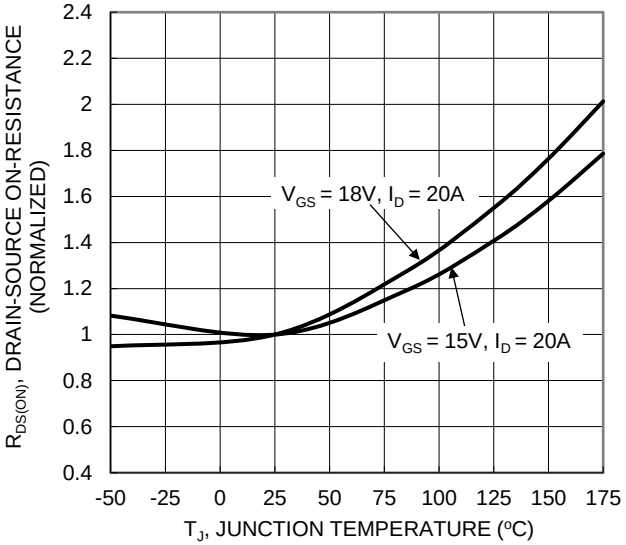


Figure 6. On-Resistance Variation with Junction Temperature

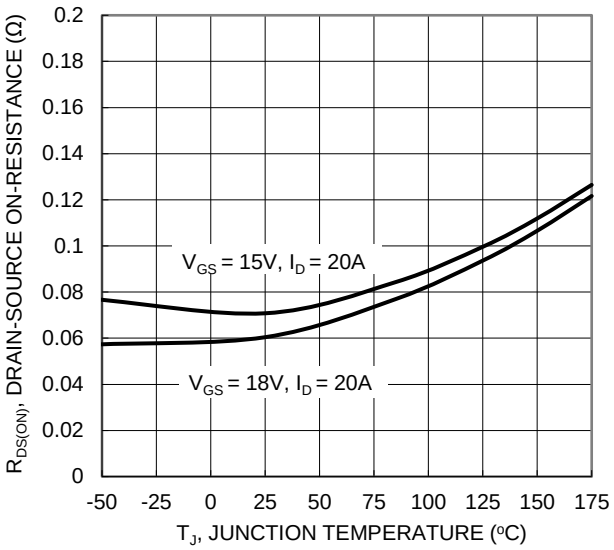


Figure 7. On-Resistance Variation with Junction Temperature

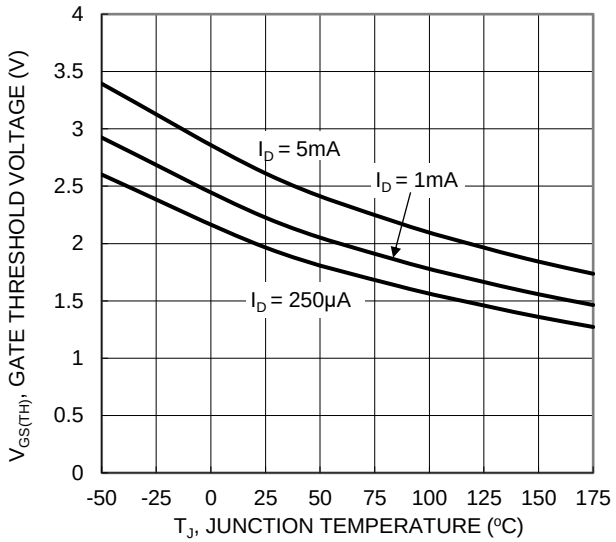


Figure 8. Gate Threshold Variation vs. Junction Temperature

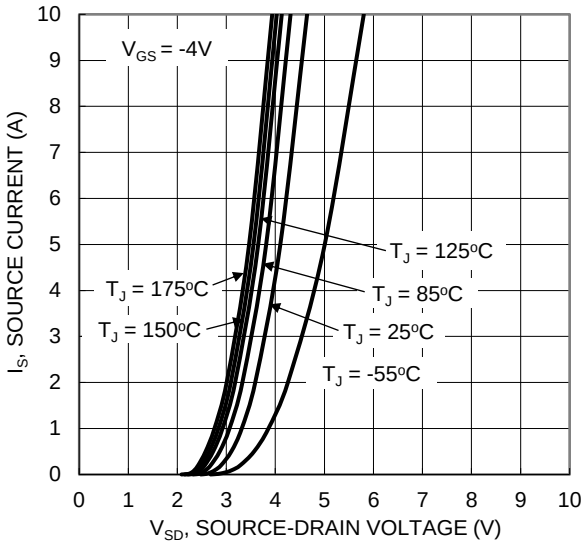


Figure 9. Diode Forward Voltage vs. Current

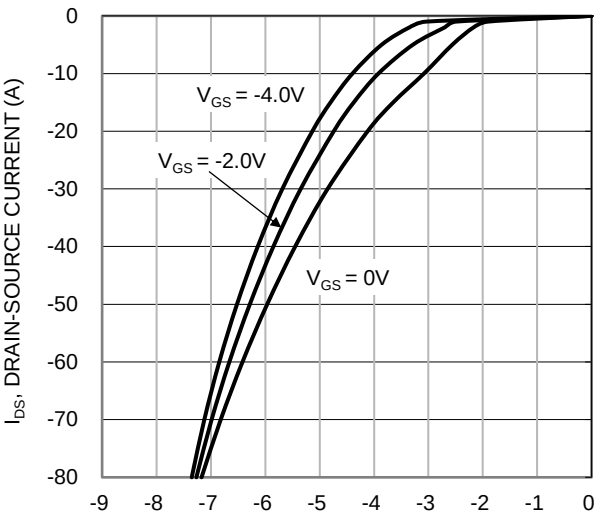


Figure 10. Body Diode Characteristic at 25°C

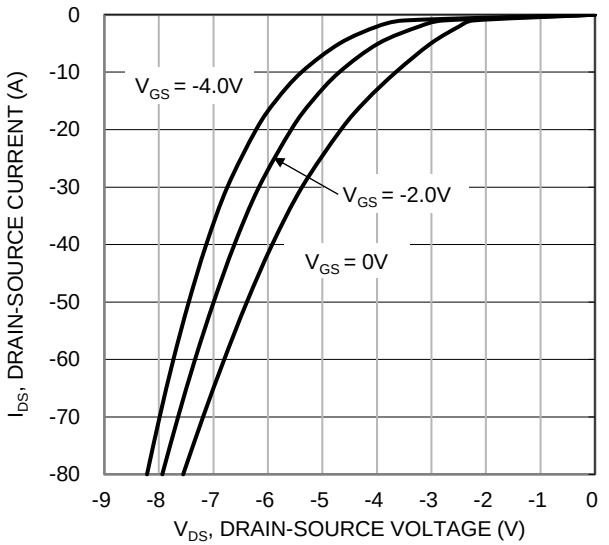


Figure 11. Body Diode Characteristic at -55°C

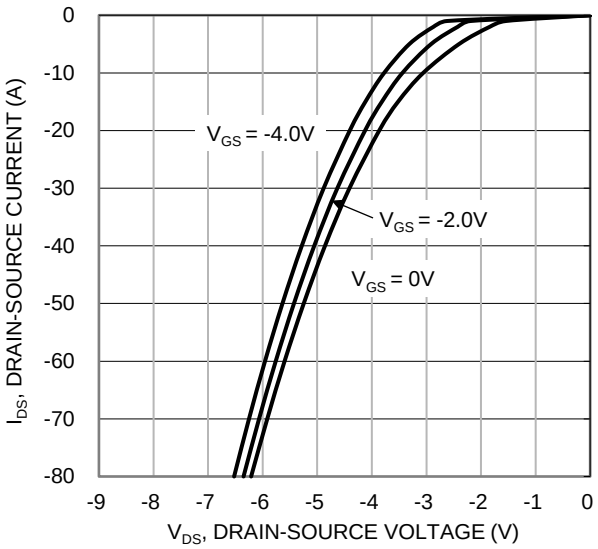


Figure 12. Body Diode Characteristic at 175°C

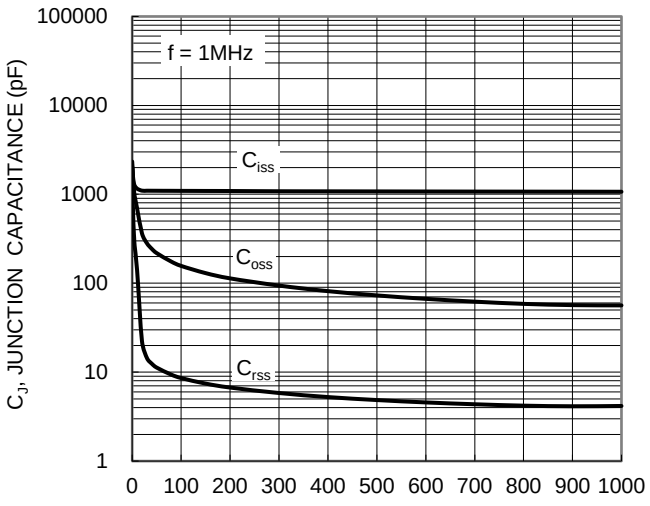


Figure 13. Typical Junction Capacitance

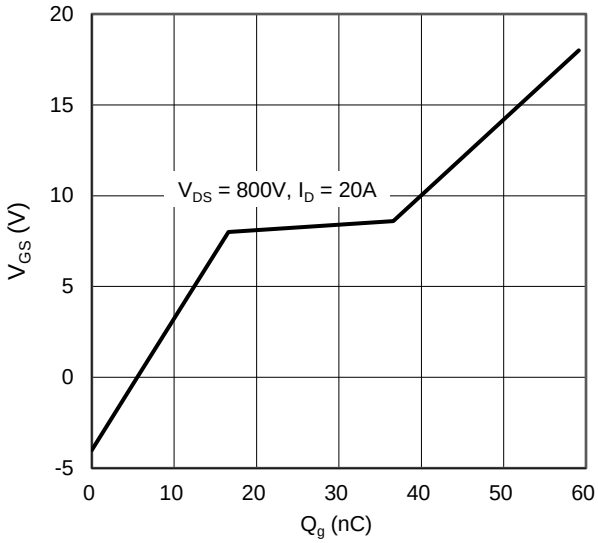


Figure 14. Gate Charge

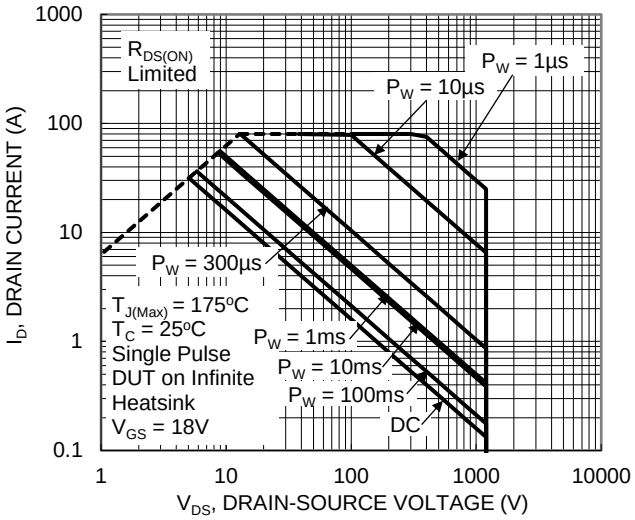


Figure 15. SOA, Safe Operation Area

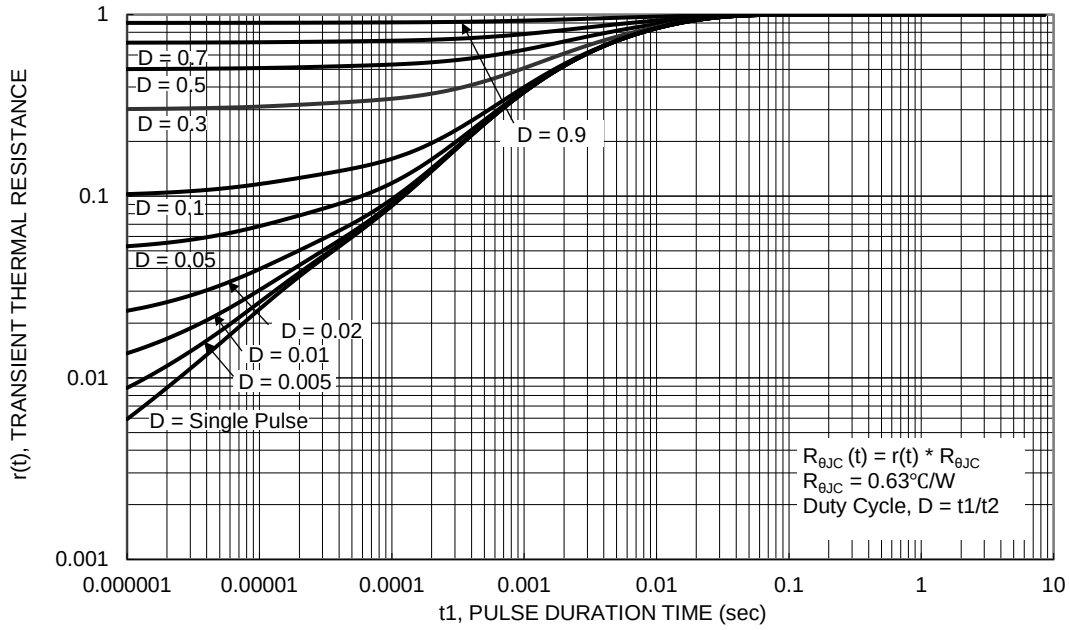
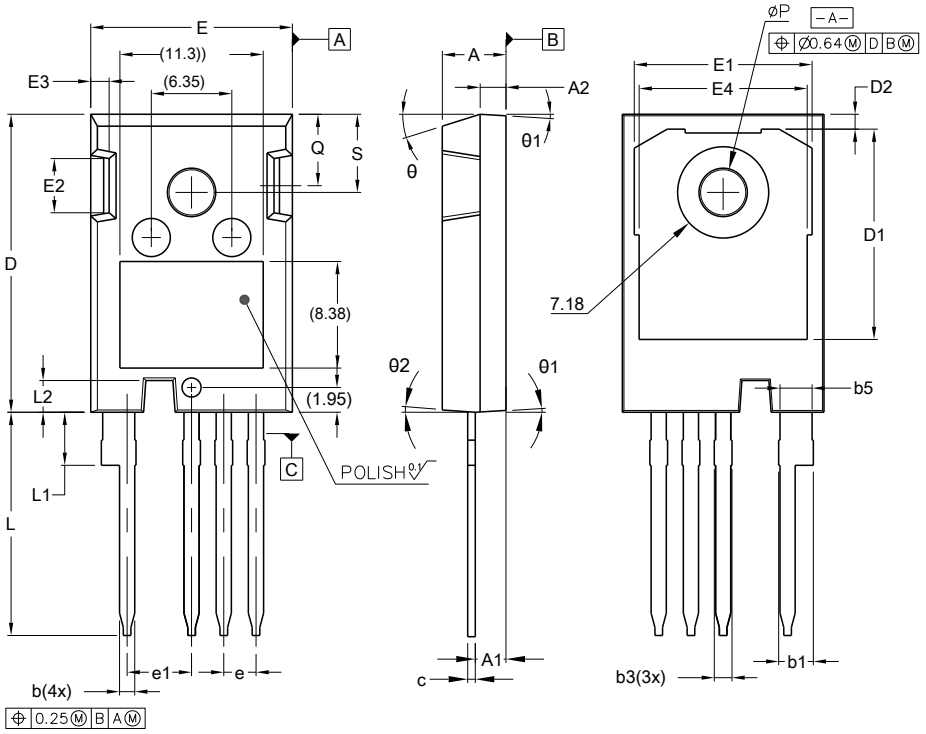


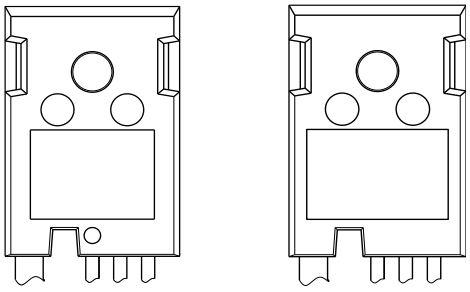
Figure 16. Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO247-4 Standard





OPTION A
(TOP VIEW)

OPTION B
(TOP VIEW)

TO247-4 Standard		
Dim	**Min**	**Max**
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b	1.07	1.33
b1	2.39	2.94
b3	1.07	1.60
b5	2.39	2.69
c	0.55	0.68
D	23.30	23.60
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.30
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	2.54 BSC	
e1	5.08 BSC	
L	17.31	17.82
L1	3.97	4.37
L2	2.35	2.65
ØP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
θ	17.5°- 20° REF	
θ1	3.5°- 5° REF	
θ2	4°- 5° REF	
All Dimensions in mm		

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